

**NIKAFLEX®**

无卤聚酰亚胺薄膜基材覆盖膜  
Halogen free polyimide film base coverlay

**CISG**

### 特点 Features

- 1** CISG耐离子迁移性、高温环境下的弯曲性优良。  
CISG has better property not only anti-Ion-migration but also in flexural strength at higher temperature.
- 2** 焊锡耐热性优良、能充分承受流焊工序、广泛用于各种电子产品。  
Because of excellent resistance to solder temperature, it bears up against flow-soldering process and consequently suitable for a wide range of parts of high-class electronic equipment.
- 3** 无卤素、不含镁材料。  
Our halogen free materials scarcely contain antimony.

### 标准产品规格 Specifications of standard Products

基材薄膜厚度 (μm) Thickness of Base Film		12.5, 25
粘合剂 Adhesive	种类 Classification	热硬化性树脂 Thermosetting Resin
	厚度 (μm) Thickness	15, 25, 35
粘合剂表面的保护材料 Releasing Material on Adhesive Surface		离型纸 Release Paper
标准尺寸 (mm) Standard Size		500 × Roll (100m)

UL FILE No:E46785 UL Recognition ( FILE No:E46785 )

### 使用注意事项 Caution

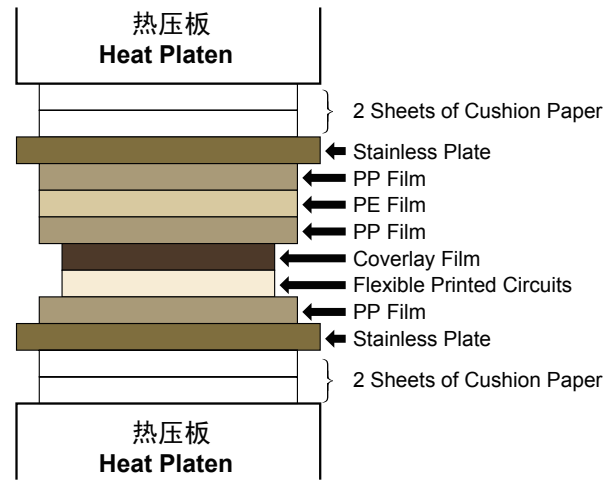
- 1** 粘合剂呈半固化状态、如果放置于常温下、则会发生快速硬化、因此请在低温（5℃以下）且湿度低于80%的条件下进行保管。  
Time and temperature rapidly promote a change from the semicured to the fully cured adhesive state, so keep coverlays at 5°C or below and at 80%RH or below.
- 2** 除部分构成外、在未开封的状态下、产品的质量保证期限为制造后4个月。  
Guaranteed period for CISG before unpacked is 4 months after manufacture with exceptions.
- 3** 用纸作为崖壑垫材时、纸中的水分会使粘合剂质量劣化、有时会导致粘合剂与薄膜剥离、因此、使用前请仔细确认。  
Moisture in press pads made of paper might make adhesiveness weaker and cause delamination of adhesive and polyimide film. If paper is used as press pads, be sure to check before using that no delamination occurs.

## 加工方法示例（压合方式） An Example of Processing Method (Press-bonding Method)

### （压合步骤）Procedures (Press-Bonding)

- 1** 常温下设置  
Setting at room temp.
- 2** 3次左右的抽空处理  
Removing Air (about 3 times)
- 3** 加压 (4MPa)  
Apply pressure (4MPa)
- 4** 升温  
Temp. Elevation
- 5** 升温至100℃时再次抽空处理  
Removing Air again at 100℃
- 6** 加压 (4MPa)  
Apply pressure (4MPa)
- 7** 升温至140~160℃时再次抽空处理  
Removing Air again at 140 to 160℃
- 8** 在160℃、4MPa的状态下保持90分钟  
Press-bonding at 160℃ under pressure of 4MPa for 90 min.
- 9** 冷却 Cooling
- 10** 取出 Taking out

### <压合设置示例> Materials assembly for Press-bonding



## CISG 性能表 Properties of CISG

聚酰亚胺薄膜12.5 μm、粘合剂厚度25 μm、CISG 1225 (2NKB)  
Model No. CISG 1225 (2NKB) (Polyimide Film 12.5μm, Adhesive 25μm)

试验项目 Test item	单位 Unit	处理条件 Treatment conditions	标准值 (平均) Our Standard Value (Average)	试验方法 Test Method
粘合剂流动性 Resin Flow	mm	A	0.18	本公司方式 Our Standard
表面电阻率 Surface Resistivity	MΩ	C-96/20/65	$4.0 \times 10^9$	JIS C 6481
		+C-96/40/90	$3.0 \times 10^8$	
体积电阻率 Volume Resistivity	MΩ-cm	C-96/20/65	$2.0 \times 10^9$	JIS C 6471
		+C-96/40/90	$1.0 \times 10^9$	
剥离强度 Peel Strength	N/mm	A	0.5	JPCA-BM-02
焊锡耐热性 Solder Heat Resistance	—	280℃ /10sec.	无异常 No change in appearance	IPC-TM-650
耐热性 Heat Resistance	—	E-24/130	无异常 No change in appearance	JIS C 6481
耐药品性 Chemical Resistance	—	23℃ /10min.	无异常 No change in appearance	JPCA-BM-02

注 (1) 粘合剂流动性、剥离强度、焊锡耐热性、耐热性、耐药品性是将35 μm电解铜箔（1盎司）的光泽面和粘合剂界面接合层压后获得的值。  
Values of resin flow, peel strength, solder heat resistance and chemical resistance are those of laminate obtained by press-bonding the untreated side of electrolytic copper foil (35μm, 1 ounce) with CISA2535 (DB).

(2) 合条件/ 温度: 160℃, 时间: 90分钟, 成型压力: 4MPa  
Press conditions: 160℃/90min./molding pressure 4MPa